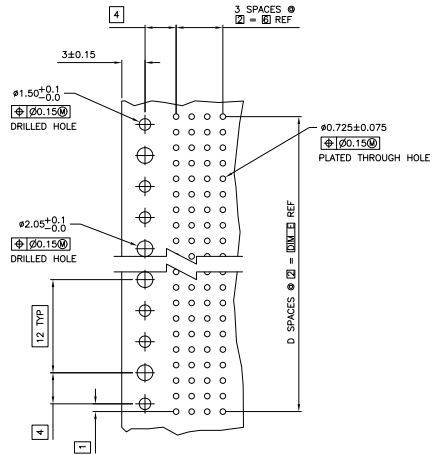
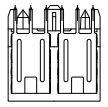
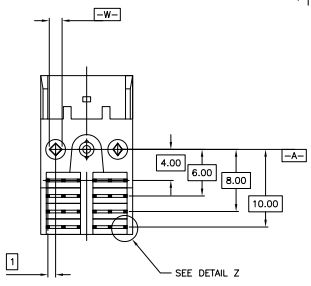
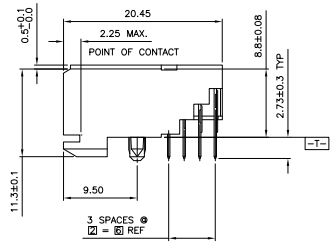
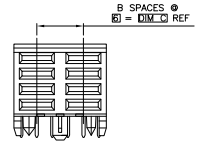
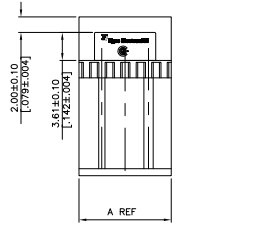


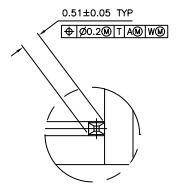
THIS DRAWING IS UNPUBLISHED  
 ALL RIGHTS RESERVED

REV	DATE	DESCRIPTION	BY	CHK	APP
AD	00	AS			
AS		REVISED PER EDD-11-004835	11MMR11	RK	HMR



RECOMMENDED CIRCUIT PATTERN  
 PER IPC-D350 TYPE II, CLASS C  
 (COMPONENT SIDE)

- △ HOUSING MATERIAL: LIQUID CRYSTAL POLYMER.
- △ CONTACT MATERIAL: PHOSPHOR-BRONZE.
- △ CONTACT FINISH:(D)
- UNDERPLATE (ENTIRE CONTACT):  
 0.00127 MIN NICKEL PER SAE-AMS-QQ-N-290
- ON MATING SURFACES:  
 FLASH GOLD PER ASTM B 488, OVER  
 0.00076 MIN PALLADIUM-NICKEL OVER UNDERPLATE, OR  
 0.00076 MIN GOLD [ER ASTM B 488 OVER UNDERPLATE.
- ON LEADS:  
 0.00381 MIN MATTE TIN PER ASTM B 545 OVER UNDERPLATE.
- LUBRICATION (ON MATING SURFACES):  
 SURFACE CONDITIONER AFTER PLATING.



DETAIL Z  
 SCALE 20:1

10	5	6	1	11.88	8	5536607-1
E	D	C	B	A	FINISH	PART NUMBER
THIS DRAWING IS A CONTROLLED DOCUMENT.						
DRAWING LEVEL:			TE Connectivity			
PROJECT FILE:			Z-PACK 2mm FB, POWER MODULE, RCPT. ASSY.			
OPERATION SPEC:			4 ROW, 2.73 mm LEAD LENGTH			
REV:			A1 00779 Q=5536607			
CUSTOMER DRAWING:			PAGE 4.1 OF 1			